

SANYO Semiconductors DATA SHEET

An ON Semiconductor Company

$LC709004A - \frac{CMOSIC}{I/O-Expander}$ for Microcontroller

Overview

The LC709004A is a peripheral IC dedicated for expanding the capability of the microcontroller (MCU) I/O ports. It interfaces with the microcontroller through synchronous serial communication. Communication with the extended I/O ports is accomplished through 16-bit parallel I/O. The extended port features include the capabilities to specify the I/O direction on a bit basis, to specify the output type (CMOS or N-channel open drain), and to specify the I/O voltage level on a port basis according to the power level of the peripheral equipment. These features make allow the LC709004A to be used in a wide variety of applications.

Features

- 4-/5-wire synchronous serial transmission and reception, and 16-bit parallel I/O
- Wide operating voltage range (2.0V to 6.0V)
- Multifunction I/O ports
 - I/O direction specification: Bit units
 - CMOS or Nch-OD output type specification: Bit units
 - Output voltage adjustment: Port (8 bits) units
- Output current: 12mA max. (capable of driving a green LED directly)
- Data transmission and reception: Can control reception of input data and transmission of output data in parallel.
- Cascaded configuration: Ports can be expanded in units of 16 bits \times n (n is the number of LSI chips).
- Packaging from: MFP24S (300mil): lead-free type (discontinued)
 - MFP24SJ (300mil): lead-free type

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Specifications

Absolute Maximum Ratings at $Ta=25^{\circ}C,\,V_{SS}=0V$

Demonster				Ratings			Linit	
Parameter	Symbol	Pin/Remarks	V _{DD} [V]		min	typ	max	Unit
Maximum supply voltage	V _{DD} max	V _{DD} , V _{DD} P1	V _{DD} =V _{DD} P1		-0.3		+7.0	
Input voltage	VI	RES, CS, DIN, CLK			-0.3		V _{DD} +0.3	
Output voltage	VO	DOUT			-0.3		V _{DD} +0.3	V
Input/output voltage	V _{IO} (1)	Port 0			-0.3		V _{DD} P1 +0.3	
	V _{IO} (2)	Port 1			-0.3		V _{DD} P1 +0.3	
High level output current		·	•					
Peak output current	IOPH(1)	Ports 0 to 1	CMOS output		-7			
	IOPH(2)	DOUT	selected Per 1 applicable pin		-13			
Mean output current	IOMH(1)	Ports 0 to 1	CMOS output		-3			
(Note 1)	IOMH(2)	DOUT	selected Per 1 applicable pin		-6			
Total output current	∑IOP0H	Port 0	Total of all applicable pins		-32			IIIA
	∑IOP1H	Port 1	Total of all applicable pins		-32			
	∑IOAH	DOUT, ports 0 to 1	Total of all applicable pins		-77			
Low level output current		·	•					
Peak output current	IOPL(1)	Ports 0 to 1	Per 1 applicable				16	
	IOPL(2)	DOUT	pin				13	
Mean output current	IOML(1)	ports 0 to 1	Per 1 applicable				7	
(Note 1)	IOML(2)	DOUT	pin				6	
Total output current	∑IOP0L	Port 0	Total of all applicable pins				32	mA
	∑IOP1L	Port 1	Total of all applicable pins				32	
	∑IOAL	DOUT, ports 0 to 1	Total of all applicable pins				77	
Power dissipation	Pd max (1)	MFP24S (300mil)	Ta=-30 to +70°C				177	
	Pd max (2)	MFP24SJ (300mil)	1				T.B.D	mVV
Operating temperature	Topr				-30		70	
Storage temperature	Tstg				-55		125	-0

Note 1: The mean output current is a mean value measured over 100ms.

Allowable Operating Conditions at $Ta=-30 \ to +70^{\circ}C, \ V_{SS}=0V$

Deremeter	Cumbal	Din/Demorke	Conditions	_	Specification (Note 3)			Linit
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	Unit
Operating supply voltage	V _{DD} (1)	V _{DD}			2.0		6.0	
	V _{DD} (2)	V _{DD} P1	Supply voltage must be within V _{DD} (1)'s specification.	2.0 to 6.0	V _{DD} -3.0		V _{DD}	
High level input voltage	V _{IH} (1)	DIN, ports 0 to 1		4.5 to 6.0	0.3V _{DD} +0.7		V _{DD} Px	
	V _{IH} (2)	DIN, ports 0 to 1		2.0 to 6.0	0.3V _{DD} +0.7		V _{DD} Px	
	V _{IH} (3)	RES, CS, CLK		4.5 to 6.0	0.4V _{DD} +0.7		V _{DD}	V
	V _{IH} (4)	RES, CS, CLK		2.0 to 6.0	0.4V _{DD} +0.7		V _{DD}	
Low level input voltage	V _{IL} (1)	DIN, ports 0 to 1		4.5 to 6.0	V _{SS}		0.2V _{DD} +0.1	
	V _{IL} (2)	DIN, ports 0 to 1		2.0 to 6.0	V _{SS}		0.2V _{DD} +0.1	
	V _{IL} (3)	RES, CS, CLK		4.5 to 6.0	V _{SS}		0.1V _{DD} +0.2	
	V _{IL} (4)	RES, CS, CLK		2.0 to 6.0	V _{SS}		0.1V _{DD} +0.2	

Note 3: V_{DD}Px denote the power supply pin (V_{DD}P1) for port pins.

	0			(Note 3)		Ratings			
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	V _{DD} Px[V]	min	typ	max	Unit
High level input current	Чн	RES, CS, CLK, Ports 0 to 1	VIN ^{=V} DD (including output Tr. off leakage current)	2.0 to 6.0				10	
Lower level input current	Ι _{ΙL}	RES, CS, CLK, Ports 0 to 1	VIN=VSS (including output Tr. off leakage current)	2.0 to 6.0		-10			μΑ
High level output	V _{OH} (1)	Ports 0	I _{OH} =-2mA	2.0 to 6.0	4.5 to 6.0	V _{DD} Px-0.5			
voltage	V _{OH} (2)		I _{OH} =-5mA	2.0 to 6.0	4.5 to 6.0	V _{DD} Px-1.0			
	V _{OH} (3)		I _{OH} =-1mA	2.0 to 6.0	2.0 to 6.0	V _{DD} Px-0.5			
	V _{OH} (4)	Ports 1	I _{OH} =-2mA	2.0 to 6.0	4.5 to 6.0	V _{DD} Px-0.5			
	V _{OH} (5)		I _{OH} =-5mA	2.0 to 6.0	4.5 to 6.0	V _{DD} Px-1.0			
	V _{OH} (6)		I _{OH} =-1mA	2.0 to 6.0	2.0 to 6.0	V _{DD} Px-0.5			
	V _{OH} (7)	DOUT	I _{OH} =-5mA	4.5 to 6.0		V _{DD} Px-0.5			
	V _{OH} (8)		I _{OH} =-10mA	4.5 to 6.0		V _{DD} Px-1.0			
	V _{OH} (9)		I _{OH} =-2mA	2.0 to 6.0		V _{DD} Px-0.5			V
Lower level output	V _{OL} (1)	Ports 0	I _{OL} =5mA	4.5 to 6.0	2.0 to 6.0			0.4	v
voltage	V _{OL} (2)		I _{OL} =12mA	4.5 to 6.0	2.0 to 6.0			1	
	V _{OL} (3)		I _{OL} =2mA	2.0 to 6.0	2.0 to 6.0			0.4	
	V _{OL} (4)	Ports 1	I _{OL} =5mA	4.5 to 6.0	4.5 to 6.0			0.4	
	V _{OL} (5)		I _{OL} =12mA	4.5 to 6.0	4.5 to 6.0			1	
	V _{OL} (6)		I _{OL} =2mA	2.0 to 6.0	2.0 to 6.0			0.4	
	V _{OL} (7)	DOUT	I _{OL} =5mA	4.5 to 6.0				0.4	
	V _{OL} (8)		I _{OL} =10mA	4.5 to 6.0				1	
	V _{OL} (9)		I _{OL} =2mA	2.0 to 6.0				0.4	
Pull-up resistance	Rpu(1)	CS	V _{OH} =V _{SS}	4.5 to 6.0		100	230	650	kΩ
Voltage hysteresis	VHIS	RES, CS, CLK		2.0 to 6.0			0.1V _{DD}		V
Consumption current (operation stopped)	IDDSP	V _{DD} =V _{DD} P1	RES=CS=VDD CLK=DIN=VDD or VSS DOUT=open P0 to P1=open or VDD or VSS (Note 2)	2.0 to 6.0				20	μΑ
Pin capacity	CP	All pins	Other than test pin VIN=VSS f=1MHz Ta=25°C	2.0 to 6.0			10		pF

Electrical Characteristics at Ta = -30 to $+70^{\circ}C$, $V_{SS} = 0V$

Note 2: The consumption current does not include the current flowing into the port's output transistor.

Note 3: $V_{DD}Px$ denote the power supply pin ($V_{DD}P1$) for port pins.

LC709004A

Switching I/O C	Characteristics at Ta=-30 to +70°C, VDD=VDDP1, VSS=0V
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Parameter Symbol PinRemarks Conditions VDDVI mm typ max Unit Clock setup time TaCLK CS, CLK *Specified with respect to laining edge of CS, 	_					Spec	ification (N	ote 3)	
Clock satup time TSCLK CS, CLX especial contents 2.0 to 6.0 100 Chip select low level setup TSCS CS, CLX -Specified with respect to failing adge of CS. 2.0 to 6.0 100 Chip select low level hold time ThCS CS, CLX -Specified with respect to failing adge of CS. 2.0 to 6.0 100 Chip select low level hold time ThCS CS, CLX -Specified with respect to failing adge of CS. 2.0 to 6.0 100 Clock hold time ThCLK CS, CLX -Specified with respect to failing adge of CS. 2.0 to 6.0 200	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	Unit
Chip select low level hold time TaiCS CS, CLK or specific durin respect to falling edge of CS, -see Fig. 8. 2.0 to 6.0 100 1111 Chip select low level hold time ThICS CS, CLK or specific durin respect to falling edge of CS, -see Fig. 8. -specified with respect to falling edge of CS, -see Fig. 8. 2.0 to 6.0 100 - Clock hold time ThICK CS, CLK or specified with respect to falling edge of CS, -see Fig. 8. 2.0 to 6.0	Clock setup time	TsCLK	<u>CS, CLK</u>	•Specified with respect to falling edge of CS. •See Fig. 8.	2.0 to 6.0	100			
Chip select low level hold time ThCS CS, CLK -specified with respect to falling odge of CS. -see Fig. 8. 2.0 to 6.0 100 100 Clock hold time ThCLK CS, CLK -specified with respect to falling odge of CS. -see Fig. 8. 2.0 to 6.0 100 100 100 Clock hold time ThCLK CLK -specified with respect to falling odge of CS. -see Fig. 8. 2.0 to 6.0 2.00 2.00 100 Clock hold time TwCLK CLK -see Fig. 8. 2.0 to 6.0 1000 100 Clock high level pulse width TwCLK CLK -see Fig. 8. 2.0 to 6.0 2.00 1000 Chip select high level setup time TshCS CS, RES -see Fig. 8. 2.0 to 6.0 1000 100 Chip select high level setup time TwRCS CS, RES -see Fig. 8. 2.0 to 6.0 1000 100 Data setup time TsDIN DIN -specified with respect to falling edge of CLK, -see Fig. 8. 2.0 to 6.0 150 100 Data setup time TbDIN DIN -specified with respect to falling edge of CLK, -see Fig. 8. 4.5 to 6.0 300 100 Serial data oup	Chip select low level setup time	TsICS	<u>CS, CLK</u>	•Specified with respect to falling edge of CS. •See Fig. 8.	2.0 to 6.0	100			
Clock hold time ThCLK CS, CLK -Specified with respect to failing edge of CS. -See Fig. 8. 2.0 to 6.0 200 200 Clock low level pulse width Tw/CLK CLK -See Fig. 8. 4.5 to 6.0 250 200 Clock low level pulse width Tw/CLK CLK -See Fig. 8. 4.5 to 6.0 250 200 Clock high level pulse width Tw/CLK CLK -See Fig. 8. 2.0 to 6.0 1000 200 Chip select high level pulse width TshCS CS, RES -See Fig. 8. 2.0 to 6.0 1000 200 Chip select high level pulse width Tw/CLK CS, RES -See Fig. 8. 2.0 to 6.0 1000 200 Chip select high level pulse width Tw/RES CS, RES -See Fig. 8. 2.0 to 6.0 200 200 Reset low level pulse width Tw/RES CS, RES -See Fig. 8. 2.0 to 6.0 300 200 Data setup time TsDIN DIN -See Fig. 8. 2.0 to 6.0 50 2.0 to 6.0 2.0 to 6.0 2.0 to 6.0 2.0 to 6.0 2.0 to	Chip select low level hold time	ThICS	<u>CS, CLK</u>	•Specified with respect to falling edge of CS. •See Fig. 8.	2.0 to 6.0	100			
Clock low level pulse width TwiCLK CLK Page Fig. 8. (2.0 to 6.0) 4.5 to 6.0 2.50 (1.00) Clock high level pulse width TwhCLK CLK See Fig. 8. (2.0 to 6.0) 4.5 to 6.0 2.00 (1.00)	Clock hold time	ThCLK	<u>CS, CLK</u>	•Specified with respect to falling edge of CS. •See Fig. 8.	2.0 to 6.0	200			
$ \left \begin{array}{c c c c c c } \hline \begin{tabular}{ c c c c } \hline \begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Clock low level pulse width	TwICLK	CLK	•See Fig. 8.	4.5 to 6.0	250			
Index on the input of the in					2.7 to 6.0	500			
Clock high level pulse width TwhCLK CLK •See Fig. 8. 4.5 to 6.0 250 4.5 to 6.0 200 4.5 to 6.0 200 4.5 to 6.0 200 4.5 to 6.0 4.5 to 6.0 200 4.5 to 6.0 4.5 to 6.0 <t< td=""><td></td><td></td><td></td><td></td><td>2.0 to 6.0</td><td>1000</td><td></td><td></td><td></td></t<>					2.0 to 6.0	1000			
width Image: setup time Image	Clock high level pulse	TwhCLK	CLK	•See Fig. 8.	4.5 to 6.0	250			
Image: constraint of the set	width				2.7 to 6.0	500			
Chip select high level setup time TshCS CS, RES •See Fig. 8. 2.0 to 6.0 200 100 Chip select high level hold time ThhCS CS, RES •See Fig. 8. 2.0 to 6.0 100 100 Chip select low level pulse width TwiCS CS, RES •See Fig. 8. 2.0 to 6.0 100 100 Data setup time TwiRS CS, RES •See Fig. 8. 2.0 to 6.0 150 100 Data setup time TsDIN DIN •Specified with respect to falling edge of CLK, •See Fig. 8. 2.0 to 6.0 300 100 100 Data hold time ThDIN DIN •Specified with respect to falling edge of CLK, •See Fig. 8. 4.5 to 6.0 300 100 Serial data output delay time (Note 4) TdDOUT DOUT •Specified with respect to rising edge of CLK, •See Fig. 8. 2.0 to 6.0 300 100 Port data input setup time TdPOUT Port 0 to 1 •Specified with respect to rising edge of CLK, •See Fig. 8. 2.0 to 6.0 300 100 Port data input hold time TsPIN Port 0 to 1 •Specified with respect to rising ed					2.0 to 6.0	1000			
Chip select high level hold time ThACS CS, RES •See Fig. 8. 2.0 to 6.0 100 Image: constraint of the section of the sectin of the section of the section of the secting of CL.	Chip select high level setup time	TshCS	CS, RES	•See Fig. 8.	2.0 to 6.0	200			
Chip select low level pulse width TwICS CS, RES -See Fig. 8. 2.0 to 6.0 200 Image: constraint of the section o	Chip select high level hold time	ThhCS	CS, RES	•See Fig. 8.	2.0 to 6.0	100			
Reset low level pulse widthTwiRESCS, RES•See Fig. 8.2.0 to 6.0150Data setup timeTsDINDIN•Specified with respect to falling edge of CLK. •See Fig. 8.4.5 to 6.030111111111111111111111111111111111	Chip select low level pulse width	TwICS	CS, RES	•See Fig. 8.	2.0 to 6.0	200			ns
Data setup timeTsDINDIN•Specified with respect to falling edg of CLK. •See Fig. 8.4.5 to 6.030	Reset low level pulse width	TwIRES	CS, RES	•See Fig. 8.	2.0 to 6.0	150			
Data hold timeThDINDINSpecified with respect to falling edge of CLK. see Fig. 8.2.0 to 6.0501000000000000000000000000000000000000	Data setup time	TsDIN	DIN	•Specified with respect to falling	4.5 to 6.0	30			
Data hold timeThDINDIN•Specified with respect to falling edge of CLK. •See Fig. 8.4.5 to 6.0501000000000000000000000000000000000000				edge of CLK. •See Fig. 8.	2.0 to 6.0	50			
Serial data output delay time (Note 4)TdDOUTDOUTSpecified with respect to falling edge of CLK. •See Fig. 8.2.7 to 6.0150160Port data output delay timeTdPOUTDOUT•Specified with respect to falling edge of CLK. •See Fig. 8.4.5 to 6.02.0 to 6.0200Port data output delay timeTdPOUTPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.2.0 to 6.02.0 to 6.0800Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0300400Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0300160Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050160Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050160Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050160Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050160Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.2.0 to 6.050160Port	Data hold time	ThDIN	DIN	 Specified with 	4.5 to 6.0	50			
Serial data output delay time (Note 4)TdDOUTDOUTSee Fig. 8.2.0 to 6.0300Port data output delay timeTdPOUTDOUT•Specified with respect to falling edge of CLK. •See Fig. 8.4.5 to 6.0200Port data output delay timeTdPOUTPort 0 to 1•Specified with respect to rising edge of CS. •See Fig. 8.2.0 to 6.0800Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.2.0 to 6.0200Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0300Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0300Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050Port data i				respect to falling	2.7 to 6.0	150			
Serial data output delay time (Note 4)TdDOUTDOUT•Specified with respect to falling edge of CLK. •See Fig. 8.4.5 to 6.0200Port data output delay timeTdPOUTPort 0 to 1•Specified with respect to rising edge of CS. •See Fig. 8.4.5 to 6.0200Port data output delay timeTdPOUTPort 0 to 1•Specified with respect to rising edge of CS. •See Fig. 8.4.5 to 6.0200Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.2.0 to 6.0300Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0300Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.050Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •Specified with respect to rising 				•See Fig. 8.	2.0 to 6.0	300			
time (Note 4)respect to falling edge of CLK. •See Fig. 8.2.7 to 6.00400Port data output delay timeTdPOUTPort 0 to 1•Specified with respect to rising edge of CS. •See Fig. 8.4.5 to 6.00200Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.00400Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0300Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0500Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.0500Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.2.0 to 6.0500Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.2.0 to 6.0500	Serial data output delay	TdD0UT	DOUT	•Specified with	4.5 to 6.0			200	
(Note 4)edge of CLK. •See Fig. 8.End to to 0100Port data output delay timeTdPOUTPort 0 to 1•Specified with respect to rising edge of \overline{CS} . •See Fig. 8.2.0 to 6.04.5 to 6.0200Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of \overline{CK} . •See Fig. 8.4.5 to 6.0300400Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of \overline{CLK} . •See Fig. 8.4.5 to 6.03001Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of \overline{CLK} . •Specified with respect to rising edge of \overline{CLK} .2.0 to 6.0501	time			respect to falling	2 7 to 6 0			400	
Port data output delay timeTdPOUTPort 0 to 1•Specified with respect to rising edge of \overline{CS} . •See Fig. 8.4.5 to 6.0200Port data input setup timeTsPINPort 0 to 1•Specified with respect to rising edge of \overline{CLK} . •See Fig. 8.4.5 to 6.030400Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of \overline{CLK} . •See Fig. 8.4.5 to 6.030400Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of \overline{CLK} . •See Fig. 8.4.5 to 6.030400Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of \overline{CLK} . •Specified with respect to rising edge of \overline{CLK} . •Specified with respect to rising edge of \overline{CLK} . •Specified with respect to rising edge of \overline{CLK} .3004.5 to 6.050	(Note 4)			edge of CLK.	2.0 to 6.0			800	
Port data input setup timeTsPINPort 0 to 1espect to rising edge of CS. •See Fig. 8.2.0 to 6.02.0 to 6.0400Port data input hold timeThPINPort 0 to 1•Specified with respect to rising edge of CLK. •See Fig. 8.4.5 to 6.030	Port data output delay time	TdPOUT	Port 0 to 1	Specified with	4.5 to 6.0			200	
Port data input setup time TsPIN Port 0 to 1 •Specified with respect to rising edge of CLK. •See Fig. 8. 2.0 to 6.0 30 Port data input hold time ThPIN Port 0 to 1 •Specified with respect to rising edge of CLK. •See Fig. 8. 2.0 to 6.0 30 Port data input hold time ThPIN Port 0 to 1 •Specified with respect to rising edge of CLK. •See Fig. 8. 4.5 to 6.0 50 Port data input hold time ThPIN Port 0 to 1 •Specified with respect to rising edge of CLK. 2.0 to 6.0 50 Port data input hold time ThPIN Port 0 to 1 •Specified with respect to rising edge of CLK. 2.0 to 6.0 50 Port data input hold time ThPIN Port 0 to 1 •Specified with respect to rising edge of CLK. 2.0 to 6.0 300				respect to rising	2 7 to 6 0			400	
Port data input setup time TsPIN Port 0 to 1 •Specified with respect to rising edge of CLK. •Specified with respect t				edge of CS.	2.0 to 6.0			800	
Port data input hold time ThPIN Port 0 to 1 •Specified with respect to rising edge of CLK. 2.0 to 6.0 50 2.7 to 6.0 150 2.7 to 6.0 150	Port data input setup time	TsPIN	Port 0 to 1	See Fig. 8. Specified with	4.5 to 6.0	30		800	
Port data input hold time ThPIN Port 0 to 1 •Specified with respect to rising edge of CLK. 4.5 to 6.0 50 2.7 to 6.0 150				edge of CLK.	2.0 to 6.0	50			
respect to rising edge of CLK. See Fig. 8 2.0 to 6.0 300	Port data input hold time	ThPIN	Port 0 to 1	•Specified with	4.5 to 6.0	50			
edge of CLK.				respect to rising	27 to 6.0	150			
				edge of CLK.	2.0 to 6.0	300			

Note 4: The input data of P00 will be out from DOUT terminal at the first negative edge of $\overline{\text{CLK}}$ signal. Because of this, Serial data output delay time of the first clock will be the time measured from the negative edge of the $\overline{\text{CLK}}$ or the time at the input data (P00) is settled.

LC709004A

Package Dimensions

unit : mm (typ) 3112B



Package Dimensions

unit : mm (typ) 3419



Pin Assignment



SANYO: MFP24S (300mil): lead-free type/MFP24SJ (300mil): lead-free type

Block Diagram



Pin Description

Pin Name	I/O	Description	I/O Type	Reset Time State
V _{SS}	-	- power supply pin		
V _{DD} V _{DD} P1	-	 + power supply pin V_{DD} is the power supply pin for blocks other than I/O ports (P00 to P17). V_{DD}P1 is the power supply pin for port pins P00 to P17. (Notes) V_{DD}P1 must not be set higher than V_{DD} (V_{DD}P1≤V_{DD}). 		
Port 0	I/O	8-bit I/O port	Output: CMOS/Nch-OD	Hi-Z
P00 to P07		 I/O specifiable in 1 bit units. CMOS/Nch-open drain specifiable in 1 bit units. Output voltage variable in 1 port units according to V_{DD}P1 voltage. 	Input: TTL	
Port 1	I/O	8-bit I/O port	Output: CMOS/Nch-OD	Hi-Z
P10 to P17		 I/O specifiable in 1 bit units. CMOS/Nch-open drain specifiable in 1 bit units. Output voltage variable in 1 port units according to V_{DD}P1 voltage. 	Input: TTL	
DIN	I	Serial data input pin	Input: TTL	
DOUT	0	Serial data output pin	Output: CMOS	High
CLK	I	 Serial clock input pin Port data is placed on DOUT on the falling edge of this clock. The data from DIN is latched on the negative-to-positive transition of this clock. 	Input: TTL Schmidt	
CS	I	 Chip select input pin Setting this pin to the low level enables serial data to be input or output. 	Input: TTL Schmidt	
RES	Ι	 Device's system reset input pin Setting this pin to the low level initializes the internal control circuit and registers and puts DOUT in the high level and all data port pins (P00 to P17) into the Hi-Z state. 	Input: TTL Schmidt	

Port Output Types and I/O States

The output type and I/O states of the LC709004A's ports can be selected by configuring the data direction register (DDR) and data register (DTR). Port data can be taken into the LC709004A only when DDR is set to 0 (Nch-open drain) and DTR is set to 1 (Nch-Tr OFF). The ports are held high for the other settings of DDR and DTR.

Dart Nama	000	DTD	Port			
Port Name	DDR	DIR	Output Type	Input	Output	
	0	1	Nch-open drain	Enabled	Hi-Z	
P00 to P07	0	0	Nch-open drain	Disabled (High)	Low	
P10 to P17	1	1	CMOS	Disabled (High)	High	
	1	0	CMOS	Disabled (High)	Low	

Port Output Circuit



Principles of Operation

The LC709004A accomplishes data transmission and reception to and from the MCU through synchronous serial communication and performs I/O operations on the extended ports in parallel mode. Its communication modes (MCU to LC709004A by serial to parallel conversion and LC709004A to MCU by parallel to serial conversion) include the initial communication modes (modes 0 and 1) in which the LC709004A initializes itself and the data communication mode in which the LC709004A sends and receives port data. The initial communication modes are used for various communication control purposes for the first time in system operation after a power-on or system reset. In these modes, the LC709004A sets up the I/O mode and output type of the ports. The data communication mode is used for communication control after the end of the initial communication modes. In this mode, the LC709004A carries out actual port I/O operations. The port I/O mode and output type settings are stored in the data direction register (DDR). The data output state settings ("High" output, "Hi-Z" output, or "Low" output) are stored in the data register (DTR). The LC709004A's operating modes are summarized below, followed by detailed mode descriptions.

Communication Mode		Description
	Mode 0	Sets the output type of all ports to "N-ch-open drain."
Initial communication mode	Mode 1	Sets the I/O direction of the ports and the their output type to CMOS or "Nch-open-drain" on a bit basis.
Data communication mode		Sends and receives port data.

(1) Initial communication modes

• Mode 0

- 1) Setting the RES pin to the low level initializes the system, sets the DOUT pin to the high level, and sets the DDR register of all ports to 0 and the DTR register to 1. The output type of the ports is set to Nch-open drain and their I/O state (Nch-Tr=OFF) to the "Hi-Z" (input mode) state.
- 2) When the $\overline{\text{RES}}$ pin is set high (reset) and the $\overline{\text{CS}}$ pin is set and held low for a certain period (TwlCS), the DDR is fixed at 0. Subsequently, the LC709004A is placed in the data communication mode.

RES					
CS					
CLK					
DIN	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX				
DOUT					
DDR					
DTR					
P00 to P17	Hi-Z				
*DDR and DTR denote the state of the internal registers.					



- Mode 1
- 1) When the RES pin is set to the low level, the LC709004A initializes the system, sets the DOUT pin to the high level, and sets the DDR register of all ports to 0 and the DTR register to 1. The output type of the ports is set to Nch-open drain and their I/O state (Nch-Tr=OFF) to the "Hi-Z" (input mode) state.
- 2) When the $\overline{\text{RES}}$ pins is set high (reset) and the $\overline{\text{CS}}$ pin is set low, the LC709004A gets ready for serial communication.
- 3) <u>The input data at P00 is sent directly to the DOUT pin on the first falling edge of the transmission clock signal</u> <u>CLK</u>. The data at pins P01 to P17 is loaded into the shift register on the rising edge of the next clock.
- 4) Subsequently, the ports' input data, which is loaded into the shift register on the falling edge of CLK, is placed at the DOUT pin sequentially (P00→P07, P10→P17) in synchronization with the falling edges of CLK, starting at port pin P00. In parallel with this operation, when data to be placed at the ports is supplied to the DIN pin sequentially starting at the port pin P00 (P00→P07, P10→P17), it is loaded into the internal shift register in synchronization with the rising edges of CLK.
- 5) When the $\overline{\text{CS}}$ pin is set high after the rising edge of the 16th clock, the data loaded in the shift register is loaded into the DDR register which determines the I/O mode and output type of the data (serial data is loaded into the DDR register after a reset is effected). Subsequently, the LC709004A controls serial data transmission and reception in the data communication mode.

		//
RES		
CS		<u></u>
CLK		14 15
DIN	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	X P16_DRX P17_DRXXXXXXXXXXXXXX
DOUT	XXXXX YP00_DI YP01_DI YP02_DI YP03_DI YP04_D YP05_DI YP06_D YP07_DI YP10_DI YP11_DI	X P16_DI P17_DI
DDR		<u> </u>
DTR		<u></u>
P00 to P17	Hi-Z	Hi-Z
* PXX	CDR denotes the input data to the port DDR identified by PXX.	, ,
* PXX	_DI denotes the input data from the port pin identified by PXX.	



(2) Data communication mode

- 1) When the $\overline{\text{CS}}$ pin is set low with the $\overline{\text{RES}}$ pin held high, the LC709004A gets ready for serial communication. (Subsequently, processing in steps 2) and 3) are identical to steps 2) and 3) in paragraph (1)-2).
- 2) The input data at P00 is sent directly to the DOUT pin on the first falling edge of the $\overline{\text{CLK}}$ signal. Data at pins P01 to P17 is loaded into the shift register on the next rising edge of the clock.
- 3) Subsequently, the ports' input data, which is loaded into the shift register on the falling edge of CLK, is placed at the DOUT pin sequentially (P00→P07, P10→P17) in synchronization with the falling edges of CLK, starting at port pin P00. In parallel with this operation, when data to be placed at the ports is supplied to the DIN pin sequentially starting at the port pin P00 (P00→P07, P10→P17), it is loaded into the internal shift register in synchronization with the rising edges of CLK.
- 4) When the $\overline{\text{CS}}$ pin is set high after the rising edge of the 16th clock, the data loaded in the shift register is loaded into the DDR register which determines the output state of the ports and the states of all port pins (P00 to P17) are then changed (output) according to the conditions established in the DDR and DTR registers. Serial data that occurs following the initial communication mode processing is always loaded into the DTR register.



Fig. 3

5) Subsequently, the state of all port pins (P00 to P17) is updated each time the set of steps 1) to 4) described in paragraph (2) are performed.

DES		(
		/
CLK		
DIN	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	<u>X P16_D0X P17_D0X XX XX XX XX XX XX XX </u>
DOUT	P17_DI(Previous Data) X P00_DI P01_DI P02_DI P03_DI P04_DI P05_DI P06_DI P07_DI P10_DI P11_DI	X P16_DI P17_DI
DDR		<u></u>
DTR	(
P00 to P17	P00-P17_OUT (Previous Data)	P00-P17_OUT (Previous Data) P00-P17_OUT
		·

Fig. 4

Application Examples

(1) Example of a cascade configuration

Two or more LC709004A LSI chips can be cascaded to realize port expansion beyond 16 bits. Port expansion, however, need to be made in units of 16 bits \times n (n denotes the number of LSI chips).



(2) Variable port power level example

When controlling the level of I/O ports according to the power voltage level of the peripheral equipment, the user can connect the output from the power supply of the peripheral equipment directly to the power supply pins for the I/O ports. The LC709004A dispenses with the need to add an external level shifter circuit. Note the following when configuring the LC709004A in this way:

Note 5:

- V_{DD}P1: The voltage level of V_{DD}P1 must not be higher than that of V_{DD} (V_{DD}P1 \leq V_{DD}).
- The input level of all ports (P00 to P17) is dependent on the V_{DD} power source; it depends on none of the power sources V_{DD}P1.
- * Be sure to check the electrical characteristics of the LC709004A.



Fig. 6

Example of Placing Bypass Capacitors between VDD and VSS Terminals





In the case of using single voltage source as showing in the Fig.7 (a), you must connect a bypass capacitor (C1, about 0.1μ F) between V_{DD} and V_{SS}. When connecting the capacitor (C1) and V_{DD}-V_{SS}, use a thick wire, and try to make its length as short as possible: moreover, try to make the impedance of V_{DD}-C1 and V_{SS}-C1 equal. In addition, when using several voltage sources as showing in the Fig.7 (b), it is suggested to connect the bypass capacitor to each set of the voltage terminals.



Fig. 8: Reset Circuit



Fig. 9: Serial I/O and Parallel Data I/O Timing Diagram

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